

HD74LS76A

Dual J-K Flip-Flops (with Preset and Clear)

REJ03D0417-0300 Rev.3.00 Jul.22.2005

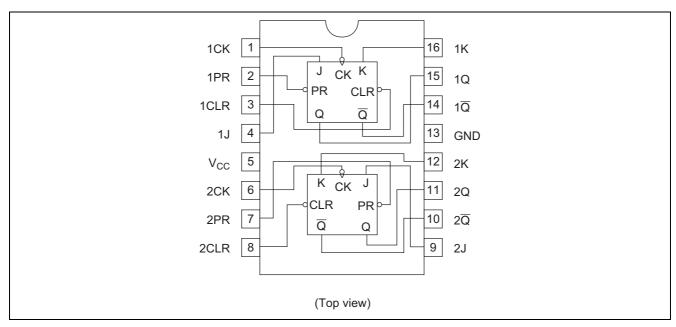
Features

• Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LS76AP	DILP-16 pin	PRDP0016AE-B (DP-16FV)	Р	_
HD74LS76ARPEL	SOP-16 pin(JEDEC)	PRSP0016DG-A (FP-16DNV)	RP	EL(2,500 pcs/reel)

Note: Please consult the sales office for the above package availability.

Pin Arrangement

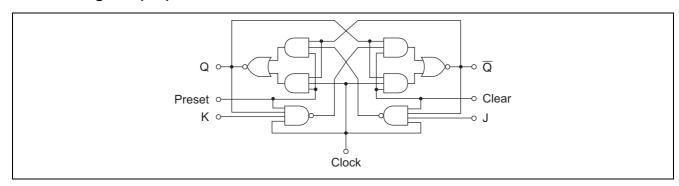


Function Table

			Out	puts		
Preset	Clear	Clock	J	K	Q	Q
L	Н	X	Х	X	Н	L
Н	L	X	Х	X	L	Н
L	L	X	Х	X	H*	H*
Н	Н	\downarrow	L	L	Q_0	\overline{Q}_0
Н	Н	\downarrow	Н	L	Н	L
Н	Н	\downarrow	L	Н	L	Н
Н	Н	\	Н	Н	Τος	ggle
Н	Н	Н	Х	Х	Q_0	\overline{Q}_0

H; high level, L; low level, X; irrelevant, \downarrow ; transition from high to low level,

Block Diagram (1/2)



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage	V _{CC}	7	V
Input voltage	V _{IN}	7	V
Power dissipation	P _T	400	mW
Storage temperature	Tstg	-65 to +150	°C

Note: Voltage value, unless otherwise noted, are with respect to network ground terminal.

Recommended Operating Conditions

Item		Symbol	Min	Тур	Max	Unit		
Supply voltag	Supply voltage		4.75	5.00	5.25	V		
Output ourror	0.1.1		the state of the s		_	_	-400	μΑ
Output curren	ıı	I _{OL}	_	_	8	mA		
Operating ten	nperature	Topr	-20	25	75	°C		
Clock frequer	псу	f _{clock}	0	_	30	MHz		
Pulse width	Clock High	t _w	20	_	_	no		
Puise width	Clear Preset Low	t _w	25	_	_	ns		
Sotup time	"H" Data		20↓	_	_	no		
Setup time	"L" Data	t _{su}	20↓	_	_	ns		
Hold time		t _h	0↓	_	_	ns		

Q₀; level of Q before the indicated steady-state input conditions were established.

 $[\]overline{Q}_0$; complement of \overline{Q}_0 or level of Q before the indicated steady-state input conditions were established.

Toggle; each output changes to the complement of its previous level on each active transition indicated by \downarrow .

^{*} This configuration is nonstable; that is, it will not persist when preset and clear inputs return to their inactive (high) level.

Electrical Characteristics

 $(Ta = -20 \text{ to } +75 \text{ }^{\circ}\text{C})$

Item		Symbol	min.	typ.*	max.	Unit	Condition		
Input voltage		V_{IH}	2.0	_	_	V			
Input voltage	put voltage		_	_	0.8	V			
O. daniel and have		V _{OH}	2.7			>	V_{CC} = 4.75 V, V_{IH} = 2 V, V_{IL} = 0.8 V, I_{OH} = -400 μ A		
Output voltag	е	\/		_	0.5	V	$I_{OL} = 8 \text{ mA}$ $V_{CC} = 4.75 \text{ V}, V_{IH} = 2 \text{ V},$		
		V _{OL}	_	_	0.4	V	$I_{OL} = 4 \text{ mA}$ $V_{IL} = 0.8 \text{ V}$		
	J, K		_	_	20				
	Clear		_	_	60		V _{CC} = 5.25 V, V _I = 2.7 V		
	Preset	I _{IH}	_	_	60	μΑ	V _{CC} = 5.25 V, V ₁ = 2.7 V		
	Clock	_	_	_	80				
	J, K	- I _{IL} **	_	_	-0.4	mA	V _{CC} = 5.25 V, V _I = 0.4 V		
Input	Clear		_	_	-0.8				
current	Preset		_	_	-0.8				
	Clock		_	_	-0.8				
	J, K		_	_	0.1				
	Clear] ,	_	_	0.3	mA	$V_{CC} = 5.25 \text{ V}, V_1 = 7 \text{ V}$		
	Preset	- Iı	_	_	0.3		V _{CC} - 5.25 V, V ₁ - 7 V		
	Clock		_	_	0.4				
Short-circuit output current		los	-20	_	-100	mA	V _{CC} = 5.25 V		
Supply current***		Icc		4	6	mA	V _{CC} = 5.25 V		
Input clamp v	oltage	V _{IK}	_		-1.5	V	V _{CC} = 4.75 V, I _{IN} = –18 mA		

Notes: * V_{CC} = 5 V, Ta = 25°C

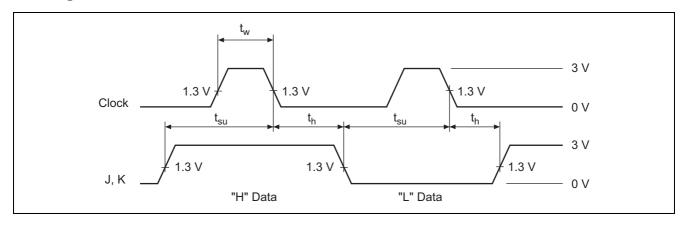
At the time of measurement, the clock input is grounded.

Switching Characteristics

$$(V_{CC} = 5 \text{ V}, \text{Ta} = 25^{\circ}\text{C})$$

Item	Symbol	Inputs	Outputs	min.	typ.	max.	Unit	Condition
Maximum clock frequency	f _{max}			30	45		MHz	
	t _{PLH}	Clear		_	15	20	ns	C_L = 15 pF, R_L = 2 kΩ
Propagation delay time	t _{PHL}	Preset Clock	Q, \overline{Q}		15	20	ns	

Timing Definition



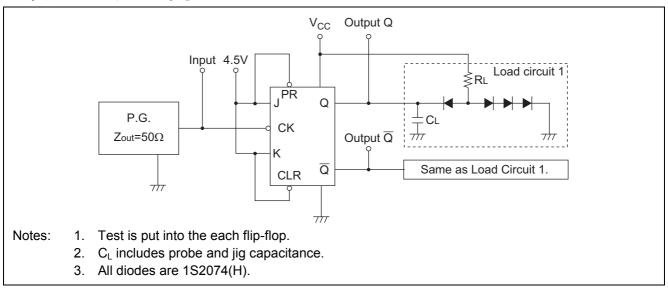
^{**} I_{IL} should not be measured when preset and clear inputs are low at same time.

^{***} With all outputs open, I_{CC} is measured with the Q and $\overline{\text{Q}}$ outputs high in turn.

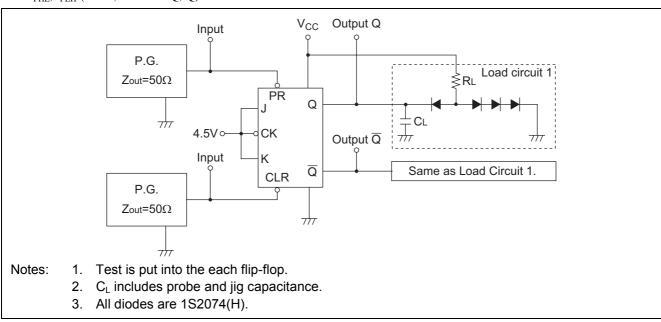
Testing Method

Test Circuit

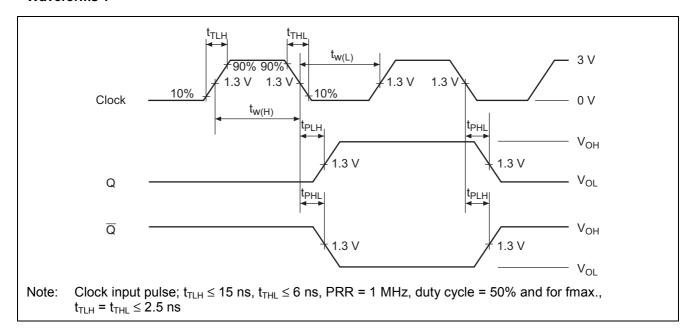
1. f_{max} , t_{PLH} , t_{PHL} , (Clock \rightarrow Q, \overline{Q})



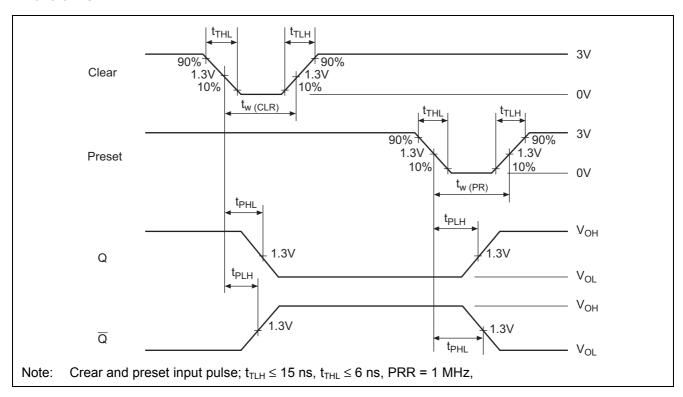
2. t_{PHL} , t_{PLH} (Clear, Preset $\rightarrow Q$, \overline{Q})



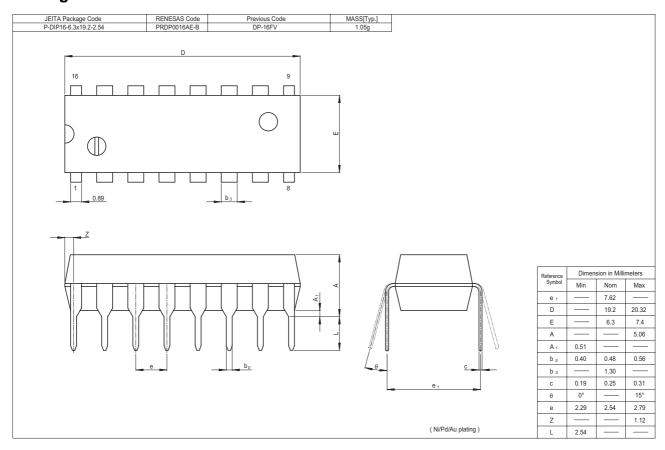
Waveforms 1

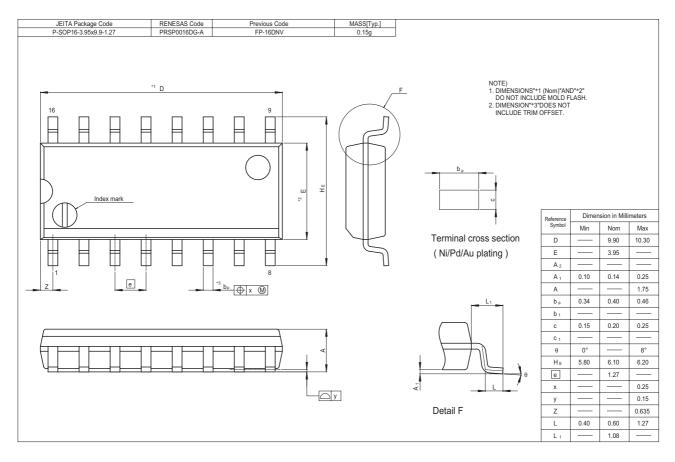


Waveforms 2



Package Dimensions





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Renesas Technology Malaysia Sdn. Bhd.

Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No.18, Jalan Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia Tel: <603> 7955-9390, Fax: <603> 7955-9510